

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re Reissue Patent Application of:  
Cyprian Emeka Uzoh et al.

Reissue Application No.: Not Yet Known  
(U.S. Patent 6,297,140)

Group Art Unit: Not Yet Known

Filed: Concurrently Herewith  
(October 2, 2001)

Examiner: Not Yet Known

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**PRELIMINARY AMENDMENT**

MS REISSUE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Please amend the application as discussed below.

In The Claims:

Please amend the claims as follows:

1.( Amended) A method for plating a second metal directly to a first metal, said method comprising [the steps of]:

providing a semiconductor substrate including at least one metal feature and at least one insulating layer covering said metal feature and said substrate;

forming at least one recess in said at least one insulating layer thereby exposing at least a portion of said metal feature;

forming at least one conductive barrier layer over said insulating layer and said exposed portion of said metal feature;

forming a plating seed layer of a first metal over said at least one barrier layer;  
depositing a photoresist layer over aid plating seed layer;